AUTOMOTIVE GRADE

CS3750

100mA Dual H-Bridge Air-Core Gauge Driver

Description

The CS3750 is a dual H-bridge four quadrant air-core gauge driver. The IC provides all the functions necessary to drive a tachometer or speedometer as part of a microprocessor based multiplexed system. Digital input control eliminates the need for any analog calibration of the gauge.

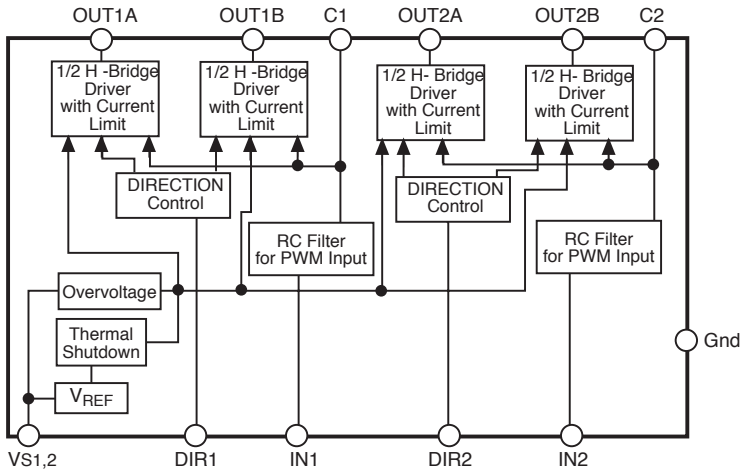
The controlling microprocessor sends out a PWM signal to each H bridge driver input (IN1, IN2). The PWM signal duty cycle is proportional to the H–bridge output. Output current (100mA max) direction is controlled by the DIRECTION input. PWM switching noise is minimized at each half bridge by an internal RC filter and external programmable capacitor.

The CS3750 is protected against 50V load dump, over voltage and thermal runaway fault conditions. Any of these faults causes the IC to shut down. Each high side of the output driver is current limited. A short circuit condition in one driver does not affect the others.

Absolute Maximum Ratings

Supply Voltage .....7.5V to +16V
Internal Power Dissipation.....Internally limited
Logic Input Voltages .....–0.3V to 6.5V
Junction Temperature Range .....–40°C to +150°C
Storage Temperature Range .....–55°C to +165°C
Lead Temperature Soldering
Wave Solder (through hole styles only).....10 sec. max, 260°C peak
Electrostatic Discharge (Human Body Model).....8kV

Block Diagram

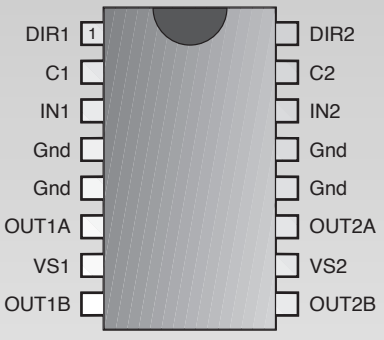


Features

- 2 Independent NPN H-Bridge Drivers
- No Analog Trim Required
- Used in Multiplexed Systems
- Quiet Gauge Operation
- Programmable Slew Rate Minimizes Switching Noise
- Fault Protection
  - Over Voltage
  - Thermal Shutdown
  - Short Circuit

Package Options

16 Lead PDIP
(internally fused leads)



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Electrical Characteristics: 7.5V <= V_{CC}<=15V; -40°C ≤ T_A ≤ +85°C unless otherwise specified.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
■ Output Stage					
V_{OUT} Saturation Voltage	I_{OUT}=100mA; V_{IN}=0V		0.25	0.50	V
(Low Side)	I_{OUT}=1mA; V_{IN}=0V		0.01	0.10	V
V_{OUT} Offset Voltage	V_C=5V; I_{OUT}=-30mA		15	50	mV
V_{OUT} Saturation High Side	V_{IN}=5V;I_{OUT}=-100mA	VS-2	VS-1.5	VS	V
Low Side	V_{IN}=0V;I_{OUT}=-1mA		0.02	0.10	V
V_{OUT} Differential	V_C=5V, I_{OUT}=-100mA			100	mV
Matching Voltage					
Supply Current	V_{IN}=V_{DIR}=0;		23	45	mA
■ Input Stage					
V_{IN} LOW	V_{IN} decreasing; V_{DIR}=0V	0.8	1.9		V
HIGH	V_{IN} increasing; V_{DIR}=0V		2.0	3.5	V
Hysteresis	V_{DIR}=0V		100		mV
I_{IN} LOW	V_{IN}=0.8V; V_{DIR}=0V		20	100	µA
HIGH	V_{IN}=3.5V		0.4	100.0	µA
Output Slew Rate with respect to input	V_{IN}=250Hz; R_{LOAD}=150Ω		0.2	0.8	V/us
Output Turn on Delay with respect to input	V_{IN}=250Hz; R_{LOAD}=150Ω, note 1		1.5	6	µs
Output Turn off Delay with respect to input	V_{IN}=250Hz; R_{LOAD}=150Ω, note 2		2.4	9	µs
■ Direction					
V_{DIR} LOW	V_{IN}=5V; V_{DIR} decreasing	0.8	1.9		V
HIGH	V_{IN}=5V; V_{DIR} increasing		2.0	3.5	V
Hysteresis	V_{IN}=5V		100		mV
I_{DIR} LOW	V_{IN}=0V; V_{DIR}=0.8V		40	100	µA
HIGH	V_{IN}=0V; V_{DIR}=3.5V		0.4	100	µA
Output Slew Rate with respect to DIR	V_{IN}=5V; f_{DIR}=250Hz; C=0µF	0.2	1.5		V/µs
Output Fall Time with respect to DIR	V_{IN}=0V; V_{DIR}=0V; C=0µF		0.2	2.0	µs
Output Turn on Delay with respect to DIR	V_{IN}=5V; R_{LOAD}=150Ω V_{DIR}=250Hz; C=0µF, note 1		1	6	µs
Output Turn off Delay with respect to DIR	V_{IN}=5V; R_{LOAD}=150Ω V_{DIR}=250Hz; C=0µF, note 2		2.5	9	µs
■ Protection Functions					
I_{OUT} Current Limit (High Side Only)	V_{IN}=5V	100	225		mA
Over Voltage Threshold	V_{IN}=5V	17.0	21.5	26.0	V
Hysteresis			0.5		V
Thermal Shutdown			160		°C
Hysteresis			20		°C

Note 1: Time required for output signal to rise to 90% of its amplitude after input signal switches.

Note 2: Time required for output signal to decrease to 10% of its amplitude after input signal switches.

Package Pin Description

PACKAGE PIN #	PIN SYMBOL	FUNCTION
16L PDIP *(internally fused leads)*		
1	DIR1	CMOS compatible input pin controls direction of current through OUT1
2	C1	RC filter capacitor for OUT1 connected to Ground
3	IN1	CMOS compatible input pin controls output OUT1A and 1B
4,5,12,13	Gnd	Ground connection
6	OUT1A	One half of H-bridge output stage 1
7	VS1	Supply voltage
8	OUT1B	One half of H-bridge output stage 1
9	OUT2B	One half of H-bridge output stage 2
10	VS2	Supply voltage
11	OUT2A	One half of H-bridge output stage 2
14	IN2	CMOS compatible input pin controls output OUT2A and 2B
15	C2	RC filter capacitor for OUT2 connected to Ground
16	DIR2	CMOS compatible input pin controls direction of current through OUT2

Circuit Description

Output Stage

Each output stage contains 4 power NPN transistors arranged in a traditional H bridge configuration. Current flow through the two outputs (OUTxA, OUTxB) in each H-bridge is controlled by the logic signal DIRx.

PWM input signals from the microprocessor, are filtered on chip and sent to the output stage. The duty cycle of the PWM signal is proportional to output voltage. The RC filter reduces the noise of the PWM input signal by slowing its slew rate: i.e., the output signal is converted from a square wave to an exponential sawtooth waveform. An external capacitor (Cx) controls the slew rate for each H bridge.

Motor Direction Control

When the voltage on the control pin (INx) is low, both halves of the H bridge are off (Table 1). When INx is high, DIR controls the flow of current through the H-bridge. If DIRx=0, current flows from OUTxA out to the coil and back in through OUTxB. If DIRx=1, current flows from OUTxB out to the coil and back in through OUTxA.

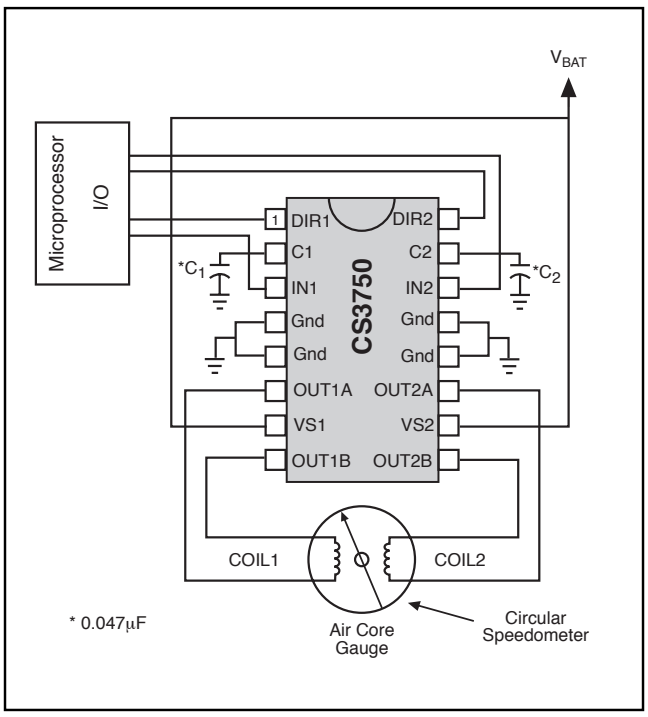
Table 1. Logic Control of H-Bridge

Input	Direction	Outputs	
INX	DIRX	OUTxA	OUTxB
0	X	0	0
1	0	1	0
1	1	0	1

Protection

The high side driver transistor in each H-bridge is current limited as a protection against a short circuit fault condition. If an over voltage or a thermal runaway fault conditions occurs, all outputs shut down.

Application Diagram



Package Specification

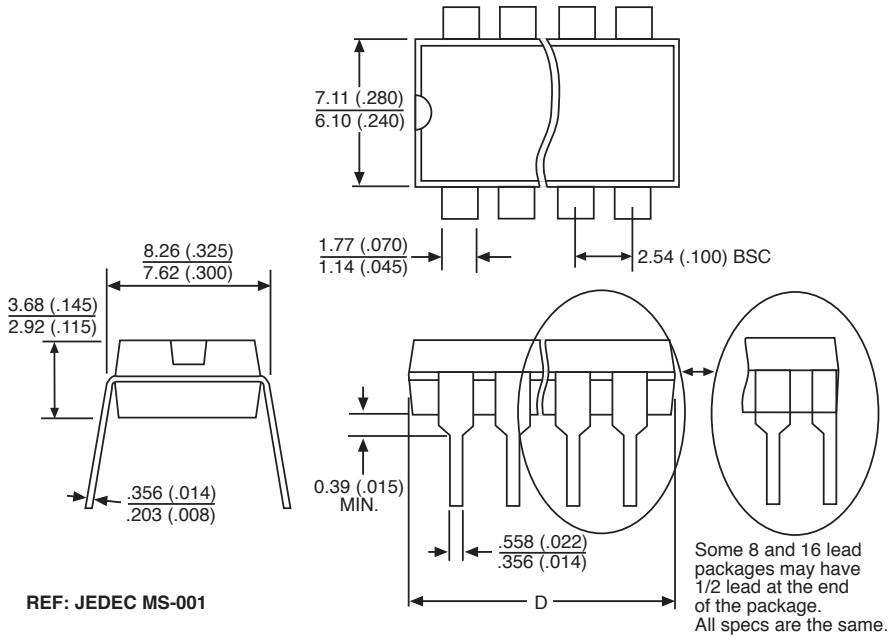
PACKAGE DIMENSIONS IN mm (INCHES)

Lead Count	D			
	Metric		English	
	Max	Min	Max	Min
16L PDIP (internally fused leads)	19.69	18.67	.775	.735

PACKAGE THERMAL DATA

Thermal Data		16L PDIP (internally fused leads)	
$R_{\Theta JC}$	typ	15	°C/W
$R_{\Theta JA}$	typ	50	°C/W

Plastic DIP (N); 300 mil wide



Ordering Information

Part Number	Description
CS3750ENF16	16L PDIP *(internally fused leads)*

Cherry Semiconductor Corporation reserves the right to make changes to the specifications without notice. Please contact Cherry Semiconductor Corporation for the latest available information.